

30 March 2004

10/008,636

L Number	Hits	Search Text	DB	Time stamp
-	6	353325.apn. 409690.apn. 354649.apn. 823948.apn. 998142.apn. 717927.apn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 11:55
-	3	6309524.pn. 6080291.pn. 6527925.pn.	USPAT	2004/03/17 14:23
-	3	5227041.pn. 6139712.pn. 6309524.pn.	USPAT	2004/03/17 14:23
-	130	205/\$.ccls. and tilt\$5 and immers\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 08:30
-	101	205/\$.ccls. and tilt\$5 and immers\$5	USPAT	2004/03/25 08:30
-	39	204/\$.ccls. and cantilevered and arcuate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 15:16
-	8	204/\$.ccls. and cantilevered.clm. and arcuate.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/25 15:16
-	78	US-4137867-\$.DID. OR US-4246088-\$.DID. OR US-4259166-\$.DID. OR US-4304641-\$.DID. OR US-4341629-\$.DID. OR US-4422915-\$.DID. OR US-4466864-\$.DID. OR US-4576685-\$.DID. OR US-4685414-\$.DID. OR US-4913085-\$.DID. OR US-5135636-\$.DID. OR US-5139818-\$.DID. OR US-5227041-\$.DID. OR US-5271953-\$.DID. OR US-5310580-\$.DID. OR US-5344491-\$.DID. OR US-5389496-\$.DID. OR US-5441629-\$.DID. OR US-5443707-\$.DID. OR US-5447615-\$.DID. OR US-5522975-\$.DID. OR US-5550315-\$.DID. OR US-5597460-\$.DID. OR US-5597836-\$.DID. OR US-5985126-\$.DID. OR US-5609239-\$.DID. OR US-5670034-\$.DID. OR US-5744019-\$.DID. OR US-5747098-\$.DID. OR US-5776327-\$.DID. OR US-5788829-\$.DID. OR US-5843296-\$.DID. OR US-5904827-\$.DID. OR US-5932077-\$.DID. OR US-6001235-\$.DID. OR US-6080291-\$.DID. OR US-6139712-\$.DID. OR US-6156167-\$.DID. OR US-6303010-\$.DID. OR US-6309520-\$.DID. OR US-6309524-\$.DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 14:19

-	41	US-4137867-\$.DID. OR US-4246088-\$.DID. OR US-4259166-\$.DID. OR US-4304641-\$.DID. OR US-4341629-\$.DID. OR US-4422915-\$.DID. OR US-4466864-\$.DID. OR US-4576685-\$.DID. OR US-4685414-\$.DID. OR US-4913085-\$.DID. OR US-5135636-\$.DID. OR US-5139818-\$.DID. OR US-5227041-\$.DID. OR US-5271953-\$.DID. OR US-5310580-\$.DID. OR US-5344491-\$.DID. OR US-5389496-\$.DID. OR US-5441629-\$.DID. OR US-5443707-\$.DID. OR US-5447615-\$.DID. OR US-5522975-\$.DID. OR US-5550315-\$.DID. OR US-5597460-\$.DID. OR US-5597836-\$.DID. OR US-5985126-\$.DID. OR US-5609239-\$.DID. OR US-5670034-\$.DID. OR US-5744019-\$.DID. OR US-5747098-\$.DID. OR US-5776327-\$.DID. OR US-5788829-\$.DID. OR US-5843296-\$.DID. OR US-5904827-\$.DID. OR US-5932077-\$.DID. OR US-6001235-\$.DID. OR US-6080291-\$.DID. OR US-6139712-\$.DID. OR US-6156167-\$.DID. OR US-6303010-\$.DID. OR US-6309520-\$.DID. OR US-6309524-\$.DID.	USPAT	2004/03/26 12:05
-	42	US-4137867-\$.DID. OR US-4246088-\$.DID. OR US-4259166-\$.DID. OR US-4304641-\$.DID. OR US-4341629-\$.DID. OR US-4422915-\$.DID. OR US-4466864-\$.DID. OR US-4576685-\$.DID. OR US-4685414-\$.DID. OR US-4913085-\$.DID. OR US-5135636-\$.DID. OR US-5139818-\$.DID. OR US-5227041-\$.DID. OR US-5271953-\$.DID. OR US-5310580-\$.DID. OR US-5344491-\$.DID. OR US-5389496-\$.DID. OR US-5441629-\$.DID. OR US-5443707-\$.DID. OR US-5447615-\$.DID. OR US-5522975-\$.DID. OR US-5550315-\$.DID. OR US-5597460-\$.DID. OR US-5597836-\$.DID. OR US-5985126-\$.DID. OR US-5609239-\$.DID. OR US-5670034-\$.DID. OR US-5744019-\$.DID. OR US-5747098-\$.DID. OR US-5776327-\$.DID. OR US-5788829-\$.DID. OR US-5843296-\$.DID. OR US-5904827-\$.DID. OR US-5932077-\$.DID. OR US-6001235-\$.DID. OR US-6080291-\$.DID. OR US-6139712-\$.DID. OR US-6156167-\$.DID. OR US-6303010-\$.DID. OR US-6309520-\$.DID. OR US-6309524-\$.DID. OR US-6645356-\$.did.	USPAT	2004/03/26 12:05
-	9727	204/\$.ccls. and (microelectr\$7 or semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/29 11:47
-	290	204/\$.ccls. and (contact adj (assembly or ring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 14:31

-	152	(204/\$.ccls. and (microelectr\$7 or semiconductor or wafer)) and (204/\$.ccls. and (contact adj (assembly or ring)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 15:12
-	7	("4269686" "5429733" "5447615" "5779492" "5833820" "5871626" "6056869").PN.	USPAT	2004/03/26 14:36
-	138	(204/\$.ccls. and (contact adj (assembly or ring))) not ((204/\$.ccls. and (microelectr\$7 or semiconductor or wafer)) and (204/\$.ccls. and (contact adj (assembly or ring))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/26 15:25
-	402	(204/\$.ccls. and (microelectr\$7 or semiconductor or wafer)) and finger	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/29 10:42
-	3620	204/\$.ccls. and ((contact or pin or finger) with (dielectric or insulat\$4 or nonconduct\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/29 11:50
-	1435	(204/\$.ccls. and ((contact or pin or finger) with (dielectric or insulat\$4 or nonconduct\$3))) and (microelectr\$7 or semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/29 11:50
-	614	((204/\$.ccls. and ((contact or pin or finger) with (dielectric or insulat\$4 or nonconduct\$3))) and (microelectr\$7 or semiconductor or wafer)) and (electroplat\$5 or electrodeposit\$5 or electrochemical\$5 or (electro adj plat\$5) or (electro adj deposit\$5) or electroetch\$5 or (electro adj etch\$5) or (electro adj polish\$5) or electropolish\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/29 11:50
-	2098	204/\$.ccls. and ((contact or pin or finger) near5 (dielectric or insulat\$4 or nonconduct\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/29 11:50
-	915	(204/\$.ccls. and ((contact or pin or finger) near5 (dielectric or insulat\$4 or nonconduct\$3))) and (microelectr\$7 or semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/29 11:50
-	396	((204/\$.ccls. and ((contact or pin or finger) near5 (dielectric or insulat\$4 or nonconduct\$3))) and (microelectr\$7 or semiconductor or wafer)) and (electroplat\$5 or electrodeposit\$5 or electrochemical\$5 or (electro adj plat\$5) or (electro adj deposit\$5) or electroetch\$5 or (electro adj etch\$5) or (electro adj polish\$5) or electropolish\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/29 11:57

-	10	204/\$.ccls. and bleck.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/29 13:48
-	2	6527925.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/29 13:48
-	821	204/224r.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:50
-	1275	204/280,286.1,297.01,297.06,297.07,297.08,297.09,297.10,297.11,297.12,297.13,297.14.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:55
-	2022	204/224r.ccls. 204/280,286.1,297.01,297.06,297.07,297.08,297.09,297.10,297.11,297.12,297.13,297.14.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 08:57
-	88	(204/224r.ccls. 204/280,286.1,297.01,297.06,297.07,297.08,297.09,297.10,297.11,297.12,297.13,297.14.ccls.) and ((post or turret or protrusion or extension) with (contact or finger or conductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 09:28
-	7	(("6699373") or ("6309520") or ("6334937") or ("6309524") or ("6645356")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/30 15:01
-	5	(("6699373") or ("6309520") or ("6334937") or ("6309524") or ("6645356")).PN.	USPAT	2004/03/30 15:01